

CG2H80060D

60 W, 8.0 GHz, GaN HEMT Die

Cree's CG2H80060D is a gallium nitride (GaN) High Electron Mobility Transistor (HEMT). GaN has superior properties compared to silicon or gallium arsenide, including higher breakdown voltage, higher saturated electron drift velocity, and higher thermal conductivity. GaN HEMTs offer greater power density and wider bandwidths compared to Si and GaAs transistors.



FEATURES

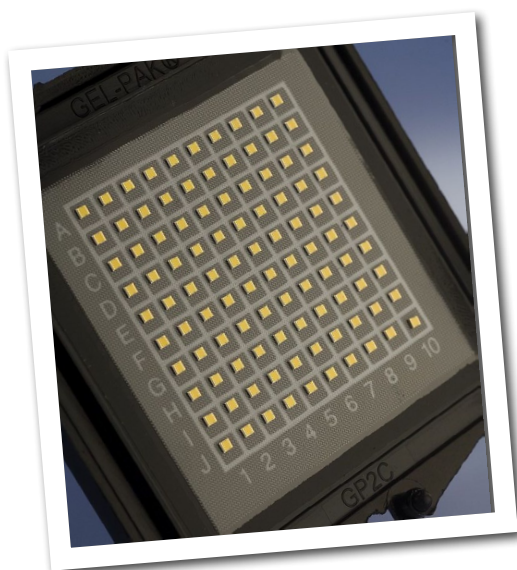
- 15 dB Typical Small Signal Gain at 4 GHz
- 12 dB Typical Small Signal Gain at 8 GHz
- 60 W Typical P_{SAT}
- 28 V Operation
- High Breakdown Voltage
- High Temperature Operation
- Up to 8 GHz Operation
- High Efficiency

APPLICATIONS

- 2-Way Private Radio
- Broadband Amplifiers
- Cellular Infrastructure
- Test Instrumentation
- Class A, AB, Linear amplifiers suitable for OFDM, W-CDMA, EDGE, CDMA waveforms



Packaging Information



- Bare die are shipped in Gel-Pak® containers.
- Non-adhesive tacky membrane immobilizes die during shipment.

Large Signal Models Available for ADS and MWO

Absolute Maximum Ratings (not simultaneous) at 25°C

| Parameter | Symbol | Rating | Units | Conditions |
|--|-----------------|-----------|-------|------------|
| Drain-source Voltage | V_{DS} | 120 | VDC | 25°C |
| Gate-source Voltage | V_{GS} | -10, +2 | VDC | 25°C |
| Storage Temperature | T_{STG} | -65, +150 | °C | |
| Operating Junction Temperature | T_J | 225 | °C | |
| Maximum Forward Gate Current | I_{GMAX} | 15 | mA | 25°C |
| Maximum Drain Current ¹ | I_{DMAX} | 6 | A | 25°C |
| Thermal Resistance, Junction to Case (packaged) ² | $R_{\theta JC}$ | 2.8 | °C/W | |
| Thermal Resistance, Junction to Case (die only) | $R_{\theta JC}$ | 1.5 | °C/W | 85°C |
| Mounting Temperature (30 seconds) | T_S | 320 | °C | 30 seconds |

Note¹ Current limit for long term, reliable operation

Note² Eutectic die attach using 80/20 AuSn mounted to a 60 mil thick CuMoCu carrier.

Electrical Characteristics (Frequency = 4 GHz unless otherwise stated; $T_C = 25^\circ\text{C}$)

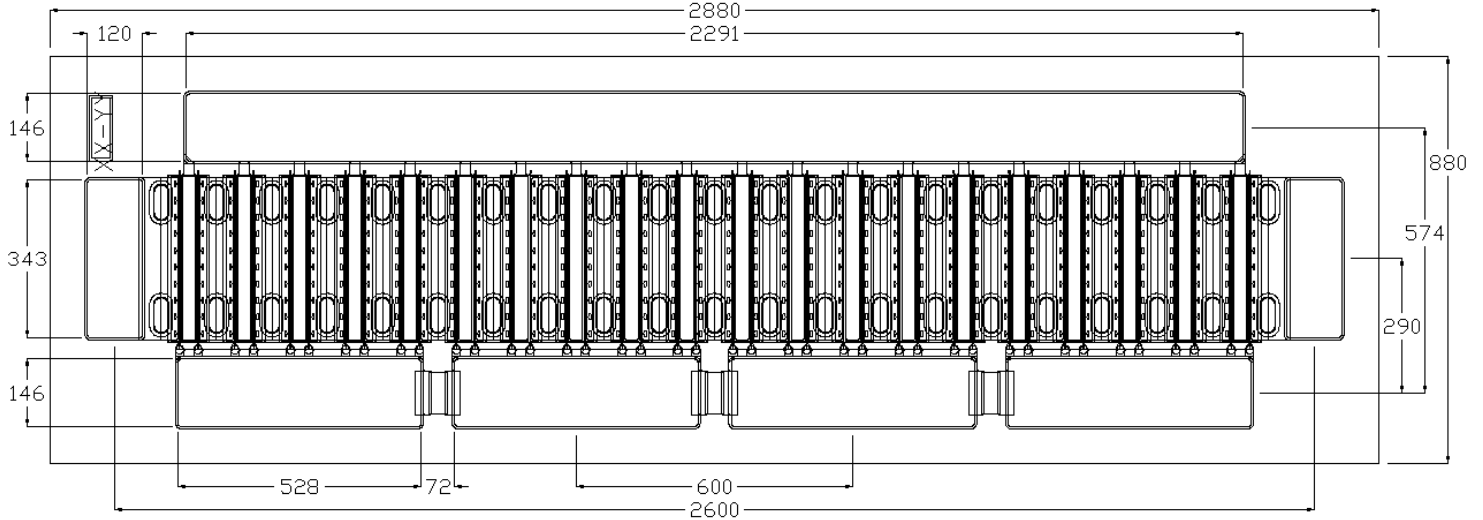
| Characteristics | Symbol | Min. | Typ. | Max. | Units | Conditions |
|---|--------------|------|------|--------|-----------------|--|
| DC Characteristics | | | | | | |
| Gate Threshold Voltage | $V_{GS(TH)}$ | -3.8 | -3.0 | -2.3 | V | $V_{DS} = 10\text{ V}, I_D = 14.4\text{ mA}$ |
| Gate Quiescent Voltage | $V_{GS(Q)}$ | - | -2.7 | - | V _{DC} | $V_{DD} = 28\text{ V}, I_{DQ} = 400\text{ mA}$ |
| Drain Current | I_{DS} | 11.6 | 14.0 | - | A | $V_{DS} = 6.0\text{ V}, V_{GS} = 2.0\text{ V}$ |
| Drain-Source Breakdown Voltage | V_{BD} | 120 | - | - | V | $V_{GS} = -8\text{ V}, I_D = 14.4\text{ mA}$ |
| On Resistance | R_{ON} | - | 0.17 | - | Ω | $V_{DS} = 0.1\text{ V}$ |
| Gate Forward Voltage | V_{G-ON} | - | 1.9 | - | V | $I_{GS} = 14.4\text{ mA}$ |
| RF Characteristics | | | | | | |
| Small Signal Gain | G_{SS} | - | 15 | - | dB | $V_{DD} = 28\text{ V}, I_{DQ} = 400\text{ mA}$ |
| Saturated Power Output ¹ | P_{SAT} | - | 60 | - | W | $V_{DD} = 28\text{ V}, I_{DQ} = 400\text{ mA}$ |
| Drain Efficiency ² | η | - | 65 | - | % | $V_{DD} = 28\text{ V}, I_{DQ} = 400\text{ mA}, P_{SAT} = 60\text{ W}$ |
| Intermodulation Distortion ³ | IM3 | - | -30 | - | dBc | $V_{DD} = 28\text{ V}, I_{DQ} = 400\text{ mA}, P_{OUT} = 60\text{ W PEP}$ |
| Output Mismatch Stress | VSWR | - | - | 10 : 1 | Ψ | No damage at all phase angles, $V_{DD} = 28\text{ V}, I_{DQ} = 400\text{ mA}, P_{OUT} = 60\text{ W CW}$ |
| Dynamic Characteristics | | | | | | |
| Input Capacitance | C_{GS} | - | 14.7 | - | pF | $V_{DS} = 28\text{ V}, V_{GS} = -8\text{ V}, f = 1\text{ MHz}$ |
| Output Capacitance | C_{DS} | - | 4.4 | - | pF | $V_{DS} = 28\text{ V}, V_{GS} = -8\text{ V}, f = 1\text{ MHz}$ |
| Feedback Capacitance | C_{GD} | - | 0.8 | - | pF | $V_{DS} = 28\text{ V}, V_{GS} = -8\text{ V}, f = 1\text{ MHz}$ |

Notes:

¹ P_{SAT} is defined as $I_G = 1.4\text{ mA}$.

² Drain Efficiency = P_{OUT} / P_{DC} .

DIE DIMENSIONS (units in microns)



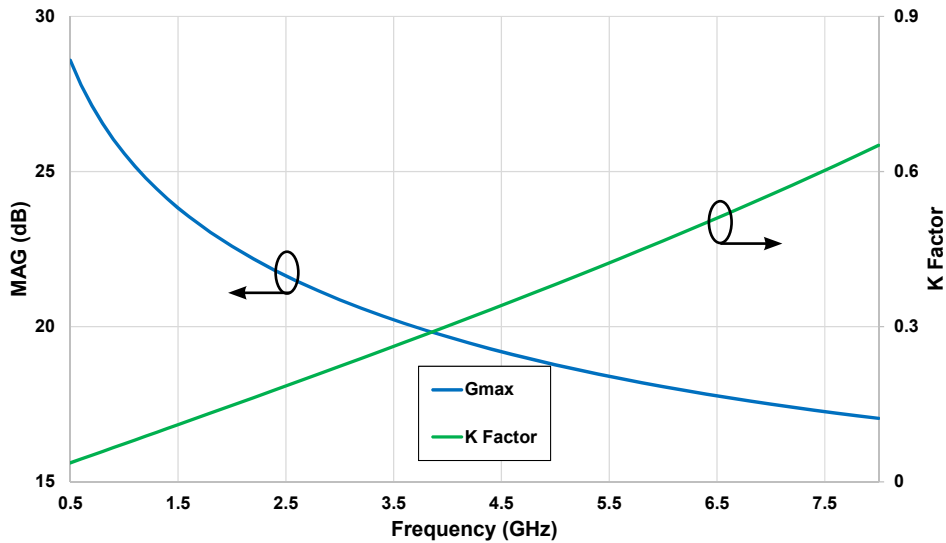
Overall die size 2880 x 880 (+0/-50) microns, die thickness 100 (+/- 10) microns.
 All Gate and Drain pads must be wire bonded for electrical connection.

Assembly Notes:

- Recommended solder is AuSn (80/20) solder. Refer to Cree's website for the Eutectic Die Bond Procedure application note at http://www.cree.com/products/wireless_documents.asp
- Vacuum collet is the preferred method of pick-up.
- The backside of the die is the Source (ground) contact.
- Die back side gold plating is 5 microns thick minimum.
- Thermosonic ball or wedge bonding are the preferred connection methods.
- Gold wire must be used for connections.
- Use the die label (XX-YY) for correct orientation.

Typical Performance

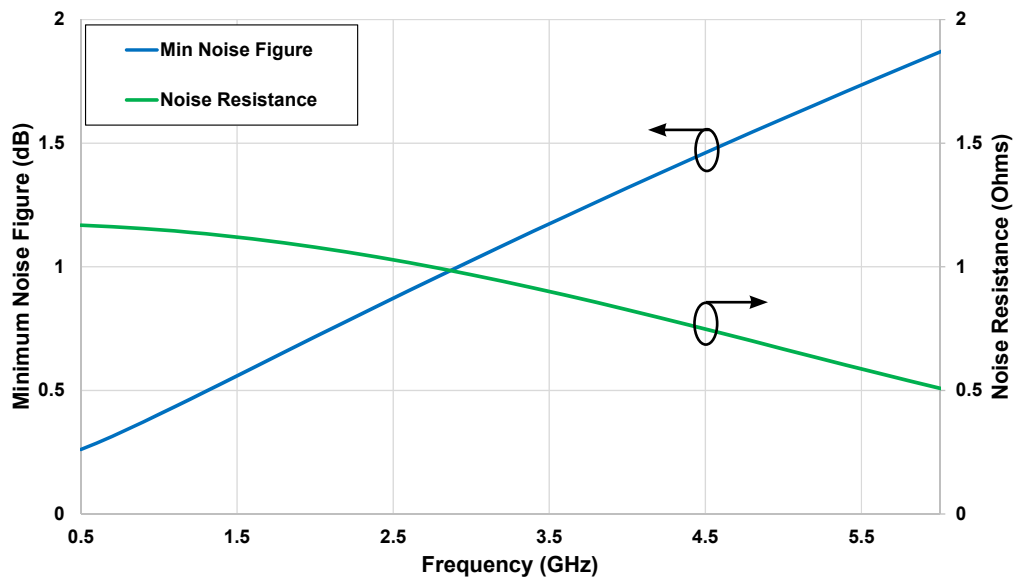
Figure 1. - Simulated Maximum Available Gain and K Factor of the CG2H80060D
 $V_{DD} = 28\text{ V}, I_{DQ} = 400\text{ mA}$



Intrinsic die parameters - reference planes at centers of gate and drain bonding pads. No wire bonds assumed.

Typical Noise Performance

Figure 2. - Simulated Minimum Noise Figure and Noise Resistance vs Frequency of the CG2H80060D
 $V_{DD} = 28\text{ V}, I_{DQ} = 400\text{ mA}$



Typical Die S-Parameters (Small Signal, $V_{DS} = 28\text{ V}$, $I_{DQ} = 400\text{ mA}$, magnitude / angle)

| Frequency | Mag S11 | Ang S11 | Mag S21 | Ang S21 | Mag S12 | Ang S12 | Mag S22 | Ang S22 |
|-----------|---------|---------|---------|---------|---------|---------|---------|---------|
| 0.5 | 0.940 | -168.07 | 9.42 | 88.99 | 0.013 | -0.29 | 0.735 | -172.83 |
| 0.6 | 0.940 | -169.98 | 7.85 | 86.72 | 0.013 | -2.42 | 0.738 | -173.30 |
| 0.7 | 0.941 | -171.35 | 6.71 | 84.72 | 0.013 | -4.27 | 0.740 | -173.54 |
| 0.8 | 0.941 | -172.36 | 5.86 | 82.90 | 0.013 | -5.95 | 0.743 | -173.64 |
| 0.9 | 0.941 | -173.15 | 5.19 | 81.20 | 0.013 | -7.51 | 0.745 | -173.64 |
| 1.0 | 0.942 | -173.77 | 4.66 | 79.58 | 0.013 | -8.98 | 0.748 | -173.59 |
| 1.1 | 0.942 | -174.28 | 4.21 | 78.04 | 0.013 | -10.38 | 0.750 | -173.50 |
| 1.2 | 0.942 | -174.70 | 3.85 | 76.54 | 0.013 | -11.73 | 0.753 | -173.38 |
| 1.3 | 0.943 | -175.06 | 3.53 | 75.10 | 0.013 | -13.03 | 0.756 | -173.25 |
| 1.4 | 0.944 | -175.36 | 3.26 | 73.69 | 0.013 | -14.30 | 0.759 | -173.10 |
| 1.5 | 0.944 | -175.62 | 3.03 | 72.31 | 0.013 | -15.53 | 0.763 | -172.96 |
| 1.6 | 0.945 | -175.85 | 2.82 | 70.97 | 0.012 | -16.73 | 0.766 | -172.81 |
| 1.8 | 0.946 | -176.24 | 2.48 | 68.37 | 0.012 | -19.04 | 0.773 | -172.53 |
| 2.0 | 0.947 | -176.55 | 2.20 | 65.86 | 0.012 | -21.26 | 0.781 | -172.28 |
| 2.2 | 0.949 | -176.81 | 1.97 | 63.45 | 0.012 | -23.38 | 0.788 | -172.05 |
| 2.4 | 0.950 | -177.03 | 1.78 | 61.12 | 0.012 | -25.42 | 0.796 | -171.87 |
| 2.6 | 0.952 | -177.23 | 1.61 | 58.88 | 0.011 | -27.37 | 0.803 | -171.72 |
| 2.8 | 0.953 | -177.41 | 1.47 | 56.72 | 0.011 | -29.24 | 0.811 | -171.61 |
| 3.0 | 0.955 | -177.57 | 1.35 | 54.64 | 0.011 | -31.03 | 0.819 | -171.54 |
| 3.2 | 0.956 | -177.73 | 1.24 | 52.63 | 0.011 | -32.75 | 0.826 | -171.50 |
| 3.4 | 0.958 | -177.87 | 1.15 | 50.70 | 0.011 | -34.39 | 0.833 | -171.49 |
| 3.6 | 0.959 | -178.02 | 1.06 | 48.84 | 0.010 | -35.96 | 0.840 | -171.51 |
| 3.8 | 0.960 | -178.15 | 0.99 | 47.04 | 0.010 | -37.46 | 0.847 | -171.55 |
| 4.0 | 0.962 | -178.28 | 0.92 | 45.32 | 0.010 | -38.90 | 0.854 | -171.61 |
| 4.2 | 0.963 | -178.41 | 0.86 | 43.65 | 0.010 | -40.27 | 0.860 | -171.69 |
| 4.4 | 0.964 | -178.54 | 0.80 | 42.05 | 0.009 | -41.58 | 0.866 | -171.78 |
| 4.6 | 0.965 | -178.67 | 0.75 | 40.50 | 0.009 | -42.83 | 0.871 | -171.89 |
| 4.8 | 0.967 | -178.79 | 0.71 | 39.01 | 0.009 | -44.02 | 0.877 | -172.01 |
| 5.0 | 0.968 | -178.91 | 0.67 | 37.57 | 0.009 | -45.16 | 0.882 | -172.14 |
| 5.2 | 0.969 | -179.03 | 0.63 | 36.18 | 0.009 | -46.25 | 0.887 | -172.27 |
| 5.4 | 0.970 | -179.15 | 0.60 | 34.85 | 0.008 | -47.29 | 0.892 | -172.42 |
| 5.6 | 0.970 | -179.27 | 0.56 | 33.55 | 0.008 | -48.29 | 0.896 | -172.57 |
| 5.8 | 0.971 | -179.39 | 0.53 | 32.30 | 0.008 | -49.23 | 0.900 | -172.72 |
| 6.0 | 0.972 | -179.51 | 0.51 | 31.10 | 0.008 | -50.14 | 0.904 | -172.87 |
| 6.2 | 0.973 | -179.62 | 0.48 | 29.93 | 0.008 | -51.00 | 0.908 | -173.03 |
| 6.4 | 0.974 | -179.74 | 0.46 | 28.80 | 0.008 | -51.83 | 0.911 | -173.19 |
| 6.6 | 0.974 | -179.85 | 0.44 | 27.70 | 0.007 | -52.62 | 0.915 | -173.35 |
| 6.8 | 0.975 | -179.96 | 0.42 | 26.64 | 0.007 | -53.37 | 0.918 | -173.51 |
| 7.0 | 0.976 | -179.92 | 0.40 | 25.62 | 0.007 | -54.09 | 0.921 | -173.67 |
| 7.2 | 0.976 | -179.81 | 0.38 | 24.62 | 0.007 | -54.78 | 0.924 | -173.83 |
| 7.4 | 0.977 | -179.70 | 0.36 | 23.65 | 0.007 | -55.44 | 0.927 | -173.98 |
| 7.6 | 0.977 | -179.59 | 0.35 | 22.71 | 0.007 | -56.06 | 0.929 | -174.14 |
| 7.8 | 0.978 | -179.48 | 0.33 | 21.80 | 0.006 | -56.66 | 0.932 | -174.30 |
| 8.0 | 0.978 | -179.37 | 0.32 | 20.91 | 0.006 | -57.23 | 0.934 | -174.45 |

Typical Die S-Parameters (Small Signal, $V_{DS} = 28\text{ V}$, $I_{DQ} = 800\text{ mA}$, magnitude / angle)

| Frequency | Mag S11 | Ang S11 | Mag S21 | Ang S21 | Mag S12 | Ang S12 | Mag S22 | Ang S22 |
|-----------|---------|---------|---------|---------|---------|---------|---------|---------|
| 0.5 | 0.954 | -169.58 | 9.41 | 89.35 | 0.010 | 0.14 | 0.772 | -175.06 |
| 0.6 | 0.954 | -171.29 | 7.84 | 87.37 | 0.010 | -1.67 | 0.774 | -175.40 |
| 0.7 | 0.954 | -172.52 | 6.71 | 85.64 | 0.010 | -3.25 | 0.775 | -175.57 |
| 0.8 | 0.954 | -173.44 | 5.86 | 84.06 | 0.010 | -4.67 | 0.777 | -175.64 |
| 0.9 | 0.954 | -174.15 | 5.20 | 82.58 | 0.010 | -5.99 | 0.778 | -175.64 |
| 1.0 | 0.955 | -174.73 | 4.67 | 81.19 | 0.010 | -7.23 | 0.780 | -175.60 |
| 1.1 | 0.955 | -175.19 | 4.23 | 79.84 | 0.010 | -8.41 | 0.782 | -175.53 |
| 1.2 | 0.955 | -175.58 | 3.86 | 78.55 | 0.010 | -9.55 | 0.783 | -175.44 |
| 1.3 | 0.955 | -175.92 | 3.55 | 77.29 | 0.010 | -10.65 | 0.785 | -175.34 |
| 1.4 | 0.956 | -176.20 | 3.29 | 76.06 | 0.010 | -11.72 | 0.787 | -175.23 |
| 1.5 | 0.956 | -176.45 | 3.06 | 74.86 | 0.009 | -12.76 | 0.789 | -175.11 |
| 1.6 | 0.956 | -176.66 | 2.85 | 73.68 | 0.009 | -13.78 | 0.791 | -174.99 |
| 1.8 | 0.957 | -177.03 | 2.51 | 71.38 | 0.009 | -15.75 | 0.796 | -174.75 |
| 2.0 | 0.958 | -177.32 | 2.24 | 69.16 | 0.009 | -17.65 | 0.801 | -174.51 |
| 2.2 | 0.959 | -177.57 | 2.01 | 67.01 | 0.009 | -19.49 | 0.806 | -174.30 |
| 2.4 | 0.959 | -177.79 | 1.82 | 64.92 | 0.009 | -21.25 | 0.811 | -174.10 |
| 2.6 | 0.960 | -177.98 | 1.66 | 62.89 | 0.009 | -22.96 | 0.816 | -173.93 |
| 2.8 | 0.961 | -178.15 | 1.53 | 60.91 | 0.009 | -24.61 | 0.822 | -173.78 |
| 3.0 | 0.962 | -178.30 | 1.40 | 59.00 | 0.009 | -26.21 | 0.827 | -173.66 |
| 3.2 | 0.963 | -178.44 | 1.30 | 57.14 | 0.008 | -27.75 | 0.832 | -173.56 |
| 3.4 | 0.964 | -178.58 | 1.20 | 55.33 | 0.008 | -29.23 | 0.838 | -173.48 |
| 3.6 | 0.965 | -178.71 | 1.12 | 53.57 | 0.008 | -30.66 | 0.843 | -173.43 |
| 3.8 | 0.966 | -178.83 | 1.05 | 51.87 | 0.008 | -32.03 | 0.848 | -173.40 |
| 4.0 | 0.967 | -178.95 | 0.98 | 50.22 | 0.008 | -33.36 | 0.854 | -173.38 |
| 4.2 | 0.967 | -179.06 | 0.92 | 48.61 | 0.008 | -34.63 | 0.859 | -173.38 |
| 4.4 | 0.968 | -179.17 | 0.86 | 47.06 | 0.008 | -35.86 | 0.863 | -173.40 |
| 4.6 | 0.969 | -179.28 | 0.81 | 45.55 | 0.007 | -37.04 | 0.868 | -173.43 |
| 4.8 | 0.970 | -179.39 | 0.77 | 44.08 | 0.007 | -38.17 | 0.873 | -173.47 |
| 5.0 | 0.971 | -179.50 | 0.72 | 42.66 | 0.007 | -39.25 | 0.877 | -173.53 |
| 5.2 | 0.971 | -179.61 | 0.69 | 41.28 | 0.007 | -40.30 | 0.881 | -173.60 |
| 5.4 | 0.972 | -179.71 | 0.65 | 39.95 | 0.007 | -41.30 | 0.886 | -173.67 |
| 5.6 | 0.973 | -179.82 | 0.62 | 38.65 | 0.007 | -42.25 | 0.890 | -173.75 |
| 5.8 | 0.973 | -179.92 | 0.59 | 37.39 | 0.007 | -43.17 | 0.893 | -173.84 |
| 6.0 | 0.974 | 179.98 | 0.56 | 36.16 | 0.006 | -44.05 | 0.897 | -173.94 |
| 6.2 | 0.975 | 179.87 | 0.53 | 34.97 | 0.006 | -44.90 | 0.901 | -174.04 |
| 6.4 | 0.975 | 179.77 | 0.51 | 33.82 | 0.006 | -45.70 | 0.904 | -174.14 |
| 6.6 | 0.976 | 179.67 | 0.48 | 32.70 | 0.006 | -46.48 | 0.907 | -174.25 |
| 6.8 | 0.976 | 179.57 | 0.46 | 31.60 | 0.006 | -47.21 | 0.910 | -174.36 |
| 7.0 | 0.977 | 179.47 | 0.44 | 30.54 | 0.006 | -47.92 | 0.913 | -174.48 |
| 7.2 | 0.977 | 179.37 | 0.43 | 29.51 | 0.006 | -48.60 | 0.916 | -174.59 |
| 7.4 | 0.978 | 179.27 | 0.41 | 28.50 | 0.006 | -49.24 | 0.919 | -174.71 |
| 7.6 | 0.978 | 179.17 | 0.39 | 27.52 | 0.006 | -49.86 | 0.921 | -174.83 |
| 7.8 | 0.979 | 179.07 | 0.38 | 26.57 | 0.005 | -50.45 | 0.924 | -174.95 |
| 8.0 | 0.979 | 178.97 | 0.36 | 25.64 | 0.005 | -51.01 | 0.926 | -175.07 |



Product Ordering Information

| Order Number | Description | Unit of Measure |
|--------------|-------------------|-----------------|
| CG2H80060D | GaN HEMT Bare Die | Each |



Disclaimer

Specifications are subject to change without notice. Cree, Inc. believes the information contained within this data sheet to be accurate and reliable. However, no responsibility is assumed by Cree for its use or for any infringement of patents or other rights of third parties which may result from its use. No license is granted by implication or otherwise under any patent or patent rights of Cree. Cree makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose. "Typical" parameters are the average values expected by Cree in large quantities and are provided for information purposes only. These values can and do vary in different applications, and actual performance can vary over time. All operating parameters should be validated by customer's technical experts for each application. Cree products are not designed, intended, or authorized for use as components in applications intended for surgical implant into the body or to support or sustain life, in applications in which the failure of the Cree product could result in personal injury or death, or in applications for the planning, construction, maintenance or direct operation of a nuclear facility. CREE and the CREE logo are registered trademarks of Cree, Inc.

For more information, please contact:

Cree, Inc.
4600 Silicon Drive
Durham, North Carolina, USA 27703
www.cree.com/rf

Sarah Miller
Marketing & Export
Cree, RF Components
1.919.407.5302

Ryan Baker
Marketing
Cree, RF Components
1.919.407.7816

Tom Dekker
Sales Director
Cree, RF Components
1.919.407.5639